MPC8250 Hardware Specifications

This document contains detailed information on power considerations, DC/AC electrical characteristics, and AC timing specifications for the MPC8250 PowerQUICC II™ communications processor.

The following topics are addressed:

The MPC8250 is available in two packages—the standard TBGA package (480 pins) and an alternate PBGA package (516 pins)—as described in Section 4, “Pinout,” and Section 5, “Package Description.” For more information on PBGA packages, contact your Freescale sales office. Note that throughout this document references to the MPC8250 are inclusive of its PBGA version unless otherwise specified.
Figure 1 shows the block diagram for the MPC8250.

![Figure 1. MPC8250 Block Diagram](image)

1 Features

The major features of the MPC8250 are as follows:

- Footprint-compatible with the MPC8260
- Dual-issue integer core
  - A core version of the EC603e microprocessor
  - System core microprocessor supporting frequencies of 150–200 MHz
  - Separate 16-Kbyte data and instruction caches:
    - Four-way set associative
    - Physically addressed
    - LRU replacement algorithm
  - PowerPC architecture-compliant memory management unit (MMU)
  - Common on-chip processor (COP) test interface
  - High-performance (4.4–5.1 SPEC95 benchmark at 200 MHz; 280 Dhrystones MIPS at 200 MHz)
— Supports bus snooping for data cache coherency
— Floating-point unit (FPU)

• Separate power supply for internal logic (1.8 V) and for I/O (3.3V)
• Separate PLLs for G2 core and for the CPM
  — G2 core and CPM can run at different frequencies for power/performance optimization
  — Internal core/bus clock multiplier that provides 1.5:1, 2:1, 2.5:1, 3:1, 3.5:1, 4:1, 5:1, 6:1 ratios
  — Internal CPM/bus clock multiplier that provides 2:1, 2.5:1, 3:1, 3.5:1, 4:1, 5:1, 6:1 ratios
• 64-bit data and 32-bit address 60x bus
  — Bus supports multiple master designs
  — Supports single- and four-beat burst transfers
  — 64-, 32-, 16-, and 8-bit port sizes controlled by on-chip memory controller
  — Supports data parity or ECC and address parity
• 32-bit data and 18-bit address local bus
  — Single-master bus, supports external slaves
  — Eight-beat burst transfers
  — 32-, 16-, and 8-bit port sizes controlled by on-chip memory controller
• 60x-to-PCI bridge
  — Programmable host bridge and agent
  — 32-bit data bus, 66 MHz, 3.3 V
  — Synchronous and asynchronous 60x and PCI clock modes
  — All internal address space available to external PCI host
  — DMA for memory block transfers
  — PCI-to-60x address remapping
• System interface unit (SIU)
  — Clock synthesizer
  — Reset controller
  — Real-time clock (RTC) register
  — Periodic interrupt timer
  — Hardware bus monitor and software watchdog timer
  — IEEE 1149.1™ JTAG test access port
• Twelve-bank memory controller
  — Glueless interface to SRAM, page mode SDRAM, DRAM, EPROM, Flash and other user-definable peripherals
  — Byte write enables and selectable parity generation
  — 32-bit address decodes with programmable bank size
  — Three user programmable machines, general-purpose chip-select machine, and page-mode pipeline SDRAM machine
  — Byte selects for 64 bus width (60x) and byte selects for 32 bus width (local)
— Dedicated interface logic for SDRAM

• CPU core can be disabled and the device can be used in slave mode to an external core

• Communications processor module (CPM)
  — Embedded 32-bit communications processor (CP) uses a RISC architecture for flexible support for communications protocols
  — Interfaces to G2 core through on-chip 32-Kbyte dual-port RAM and DMA controller
  — Serial DMA channels for receive and transmit on all serial channels
  — Parallel I/O registers with open-drain and interrupt capability
  — Virtual DMA functionality executing memory-to-memory and memory-to-I/O transfers

— Three fast communications controllers supporting the following protocols:
  – 10/100-Mbit Ethernet/IEEE 802.3® CDMA/CS interface through media independent interface (MII)
  – Transparent
  – HDLC—Up to T3 rates (clear channel)

— One multichannel controller (MCC2)
  – Handles 128 serial, full-duplex, 64-Kbps data channels. The MCC can be split into four subgroups of 32 channels each.
  – Almost any combination of subgroups can be multiplexed to single or multiple TDM interfaces up to four TDM interfaces per MCC

— Four serial communications controllers (SCCs) identical to those on the MPC860, supporting the digital portions of the following protocols:
  – Ethernet/IEEE 802.3 CDMA/CS
  – HDLC/SDLC and HDLC bus
  – Universal asynchronous receiver transmitter (UART)
  – Synchronous UART
  – Binary synchronous (BISYNC) communications
  – Transparent

— Two serial management controllers (SMCs), identical to those of the MPC860
  – Provide management for BRI devices as general circuit interface (GCI) controllers in time-division-multiplexed (TDM) channels
  – Transparent
  – UART (low-speed operation)

— One serial peripheral interface identical to the MPC860 SPI

— One inter-integrated circuit (I²C) controller (identical to the MPC860 I²C controller)
  – Microwire compatible
  – Multiple-master, single-master, and slave modes

— Up to four TDM interfaces
  – Supports one group of four TDM channels
– 2,048 bytes of SI RAM
– Bit or byte resolution
– Independent transmit and receive routing, frame synchronization
– Supports T1, CEPT, T1/E1, T3/E3, pulse code modulation highway, ISDN basic rate, ISDN primary rate, Freescale interchip digital link (IDL), general circuit interface (GCI), and user-defined TDM serial interfaces
  — Eight independent baud rate generators and 20 input clock pins for supplying clocks to FCCs, SCCs, SMCs, and serial channels
  — Four independent 16-bit timers that can be interconnected as two 32-bit timers
• PCI bridge
  — PCI Specification Revision 2.2 compliant and supports frequencies up to 66 MHz
  — On-chip arbitration
  — Support for PCI to 60x memory and 60x memory to PCI streaming
  — PCI Host Bridge or Peripheral capabilities
  — Includes 4 DMA channels for the following transfers:
    – PCI-to-60x to 60x-to-PCI
    – 60x-to-PCI to PCI-to-60x
    – PCI-to-60x to PCI-to-60x
    – 60x-to-PCI to 60x-to-PCI
  — Includes all of the configuration registers (which are automatically loaded from the EPROM and used to configure the MPC8265A) required by the PCI standard as well as message and doorbell registers
  — Supports the I2O standard
  — Hot-Swap friendly (supports the Hot Swap Specification as defined by PICMG 2.1 R1.0 August 3, 1998)
  — Support for 66 MHz, 3.3 V specification
  — 60x-PCI bus core logic which uses a buffer pool to allocate buffers for each port
  — Makes use of the local bus signals, so there is no need for additional pins


## 2 Electrical and Thermal Characteristics

This section provides AC and DC electrical specifications and thermal characteristics for the MPC8250.

### 2.1 DC Electrical Characteristics

This section describes the DC electrical characteristics for the MPC8250. **Table 1** shows the maximum electrical ratings.

#### Table 1. Absolute Maximum Ratings

<table>
<thead>
<tr>
<th>Rating</th>
<th>Symbol</th>
<th>Value</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Core supply voltage</td>
<td>VDD</td>
<td>-0.3 – 2.5 V</td>
<td>V</td>
</tr>
<tr>
<td>PLL supply voltage</td>
<td>VCCSYN</td>
<td>-0.3 – 2.5 V</td>
<td>V</td>
</tr>
<tr>
<td>I/O supply voltage</td>
<td>VDDH</td>
<td>-0.3 – 4.0 V</td>
<td>V</td>
</tr>
<tr>
<td>Input voltage</td>
<td>VIN</td>
<td>GND(-0.3) – 3.6</td>
<td>V</td>
</tr>
<tr>
<td>Junction temperature</td>
<td>T_j</td>
<td>120 °C</td>
<td></td>
</tr>
<tr>
<td>Storage temperature range</td>
<td>T_STG</td>
<td>(-55) – (+150)</td>
<td>°C</td>
</tr>
</tbody>
</table>

1 Absolute maximum ratings are stress ratings only; functional operation (see **Table 2**) at the maximums is not guaranteed. Stress beyond those listed may affect device reliability or cause permanent damage.

2 **Caution:** VDD/VCCSYN must not exceed VDDH by more than 0.4 V at any time, including during power-on reset.

3 **Caution:** VDDH can exceed VDD/VCCSYN by 3.3 V during power on reset by no more than 100 mSec. VDDH should not exceed VDD/VCCSYN by more than 2.5 V during normal operation.

4 **Caution:** VIN must not exceed VDDH by more than 2.5 V at any time, including during power-on reset.

**Table 2** lists recommended operational voltage conditions.

#### Table 2. Recommended Operating Conditions

<table>
<thead>
<tr>
<th>Rating</th>
<th>Symbol</th>
<th>Value</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Core supply voltage</td>
<td>VDD</td>
<td>1.7 – 1.9 ²</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td></td>
<td>1.7 – 2.1 ³</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>1.9 – 2.2 ⁴</td>
<td></td>
</tr>
<tr>
<td>PLL supply voltage</td>
<td>VCCSYN</td>
<td>1.7 – 1.9 ²</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td></td>
<td>1.7 – 2.1 ³</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>1.9 – 2.2 ⁴</td>
<td></td>
</tr>
<tr>
<td>I/O supply voltage</td>
<td>VDDH</td>
<td>3.135 – 3.465</td>
<td>V</td>
</tr>
<tr>
<td>Input voltage</td>
<td>VIN</td>
<td>GND(-0.3) – 3.465</td>
<td>V</td>
</tr>
<tr>
<td>Junction temperature (maximum)</td>
<td>T_j</td>
<td>105 ⁵</td>
<td>°C</td>
</tr>
<tr>
<td>Ambient temperature</td>
<td>T_A</td>
<td>0–70²</td>
<td>°C</td>
</tr>
</tbody>
</table>

1 **Caution:** These are the recommended and tested operating conditions. Proper device operating outside of these conditions is not guaranteed.

2 CPU frequency less than or equal to 200 MHz.

3 CPU frequency greater than 200 MHz but less than 233 MHz.

4 CPU frequency greater than or equal to 233 MHz.

5 Note that for extended temperature parts the range is $(-40)_{T_A} – 105_{T_j}$. 

MPC8250 Hardware Specifications, Rev. 2

Freescale Semiconductor
NOTE: Core, PLL, and I/O Supply Voltages

VDDH, VCCSYN, and VDD must track each other and both must vary in the same direction—in the positive direction (+5% and +0.1 Vdc) or in the negative direction (-5% and -0.1 Vdc).

This device contains circuitry protecting against damage due to high static voltage or electrical fields; however, it is advised that normal precautions be taken to avoid application of any voltages higher than maximum-rated voltages to this high-impedance circuit. Reliability of operation is enhanced if unused inputs are tied to an appropriate logic voltage level (either GND or VCC).

Figure 2 shows the undershoot and overshoot voltage of the 60x and local bus memory interface of the MPC8280. Note that in PCI mode the I/O interface is different.

![Figure 2. Overshoot/Undershoot Voltage](image)

Table 3 shows DC electrical characteristics.

<table>
<thead>
<tr>
<th>Characteristic</th>
<th>Symbol</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Input high voltage, all inputs except CLKin</td>
<td>VH</td>
<td>2.0</td>
<td>3.465</td>
<td>V</td>
</tr>
<tr>
<td>Input low voltage</td>
<td>VL</td>
<td>GND</td>
<td>0.8</td>
<td>V</td>
</tr>
<tr>
<td>CLKin input high voltage</td>
<td>VIHC</td>
<td>2.4</td>
<td>3.465</td>
<td>V</td>
</tr>
<tr>
<td>CLKin input low voltage</td>
<td>VILC</td>
<td>GND</td>
<td>0.4</td>
<td>V</td>
</tr>
<tr>
<td>Input leakage current, VIN = VDDH (^2)</td>
<td>IIN</td>
<td>—</td>
<td>10</td>
<td>µA</td>
</tr>
<tr>
<td>Hi-Z (off state) leakage current, VIN = VDDH (^2)</td>
<td>IOZ</td>
<td>—</td>
<td>10</td>
<td>µA</td>
</tr>
<tr>
<td>Signal low input current, VIL = 0.8 V</td>
<td>IL</td>
<td>—</td>
<td>1</td>
<td>µA</td>
</tr>
<tr>
<td>Signal high input current, VIH = 2.0 V</td>
<td>IH</td>
<td>—</td>
<td>1</td>
<td>µA</td>
</tr>
<tr>
<td>Output high voltage, IOH = −2 mA</td>
<td>VOH</td>
<td>2.4</td>
<td>—</td>
<td>V</td>
</tr>
</tbody>
</table>

MPC8250 Hardware Specifications, Rev. 2

Freescale Semiconductor
### Table 3. DC Electrical Characteristics \(^1\) (continued)

<table>
<thead>
<tr>
<th>Characteristic</th>
<th>Symbol</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>VOL = 7.0mA</td>
<td></td>
<td></td>
<td>0.4</td>
<td>V</td>
</tr>
<tr>
<td>BR</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>BG</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>A[0–31], TS</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>TT[0–4], TBST</td>
<td></td>
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<td></td>
</tr>
<tr>
<td>TSIZE[0–3]</td>
<td></td>
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<td></td>
<td></td>
</tr>
<tr>
<td>AACK</td>
<td></td>
<td></td>
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</tr>
<tr>
<td>ARTRY</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>DBG</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>DBB/IRQ3</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>D[0–63]</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>DP(0)/RSRV/EXT_BR2</td>
<td></td>
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<tr>
<td>DP(1)/IRQ1/EXT_BG2</td>
<td></td>
<td></td>
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</tr>
<tr>
<td>DP(2)/TLBISYNC/IRQ2/EXT_DBG2</td>
<td></td>
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</tr>
<tr>
<td>DP(3)/IRQ3/EXT_BR3/CKSTP_OUT</td>
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<td></td>
</tr>
<tr>
<td>DP(4)/IRQ4/EXT_BG3/CORE_SREST</td>
<td></td>
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<td></td>
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<tr>
<td>DP(5)/TBEN/IRQ5/EXT_DBG3</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>DP(6)/CSE(0)/IRQ6</td>
<td></td>
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<tr>
<td>DP(7)/CSE(1)/IRQ7</td>
<td></td>
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<tr>
<td>PSDVAC</td>
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<tr>
<td>TA</td>
<td></td>
<td></td>
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<td></td>
</tr>
<tr>
<td>TEA</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>GBC/IROT</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>CI/BADDR29/IRQ2</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>WT/BADDR30/IRQ3</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>L2_HIT/IRQ4</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>CPU_BG/BADDR31/IRQ5</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>CPU_DBG</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>CPU_BR</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>IRQ0/NMI_OUT</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>IRQ7/INT_OUT/APE</td>
<td></td>
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<td></td>
</tr>
<tr>
<td>PORESET</td>
<td></td>
<td></td>
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<td></td>
</tr>
<tr>
<td>HRESET</td>
<td></td>
<td></td>
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<tr>
<td>SRESET</td>
<td></td>
<td></td>
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</tr>
<tr>
<td>RSTCONF</td>
<td></td>
<td></td>
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</tr>
</tbody>
</table>

\(^1\) Continued from previous page.
### Electrical and Thermal Characteristics

- **I\(_{OL}\) = 5.3mA**
  - CS[0-9]
  - CS(10)/BCTL0
  - CS(11)/AP(0)
  - BADDR[27–28]
  - ALE
  - BCTL0
  - PWE(0:7)/PSDDQM(0:7)/PBS(0:7)
  - PSDA10/PGPL0
  - PSDWE/PGPL1
  - POE/PDDRAS/PGPL2
  - PSDCAS/PGPL3
  - PGTA/PUPMWAIT/PGPL4/PPBS
  - PSDAMUX/PGPL5
  - LWE[0–3]/LSDDQM[0:3]/LBS[0–3]/PCI_CFG[0–3]
  - LSDA10/LGPL0/PCI_MODCKH0
  - LSDWE/LGPL1/PCI_MODCKH1
  - LOE/LSDRAS/LGPL2/PCI_MODCKH2
  - LSDCAS/LGPL3/PCI_MODCKH3
  - LGTA/LUPMWAIT/LGPL4/LPBS
  - LSDAMUX/LGPL5/PCI_MODCK

- **I\(_{OL}\) = 3.2mA**
  - L_A14/Par
  - L_A15/FRAME/SMT
  - L_A16/TRDY
  - L_A17/TRDY/CKSTP_OUT
  - L_A18/STOP
  - L_A19/DEVSEL
  - L_A20/IDSEL
  - L_A21/PERR
  - L_A22/SERR
  - L_A23/REQ0
  - L_A24/REQ1/HSEJSW
  - L_A25/GNT0
  - L_A26/GNT1/HSELD
  - L_A27/GNT2/HSENUM
  - L_A28/RST/CORE_SRESET
  - L_A29/INTA
  - L_A30/REQ2
  - L_A31
  - LCL_D(0-31)/AD(0-31)
  - LCL_DP(0-3)/C/BE(0-3)
  - PA[0–31]
  - PB[4–31]
  - PC[0–31]
  - PD[4–31]
  - TDO

---

**Table 3. DC Electrical Characteristics**

<table>
<thead>
<tr>
<th>Characteristic</th>
<th>Symbol</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>I(_{OL}) = 5.3mA</td>
<td>V(_{OL})</td>
<td>—</td>
<td>0.4</td>
<td>V</td>
</tr>
</tbody>
</table>
2.2 Thermal Characteristics

Table 4 describes thermal characteristics.

### Table 4. Thermal Characteristics

<table>
<thead>
<tr>
<th>Characteristic</th>
<th>Symbol</th>
<th>Value</th>
<th>Unit</th>
<th>Air Flow</th>
</tr>
</thead>
<tbody>
<tr>
<td>Junction to ambient—single-layer board</td>
<td>$\theta_{JA}$</td>
<td>13</td>
<td>24</td>
<td>$^\circ$C/W</td>
</tr>
<tr>
<td></td>
<td></td>
<td>10</td>
<td>18</td>
<td>1 m/s</td>
</tr>
<tr>
<td>Junction to ambient—four-layer board</td>
<td>$\theta_{JA}$</td>
<td>11</td>
<td>16</td>
<td>$^\circ$C/W</td>
</tr>
<tr>
<td></td>
<td></td>
<td>8</td>
<td>13</td>
<td>1 m/s</td>
</tr>
<tr>
<td>Junction to board</td>
<td>$\theta_{JB}$</td>
<td>4</td>
<td>8</td>
<td>$^\circ$C/W</td>
</tr>
<tr>
<td>Junction to case</td>
<td>$\theta_{JC}$</td>
<td>1.1</td>
<td>6</td>
<td>$^\circ$C/W</td>
</tr>
</tbody>
</table>

1 Assumes no thermal vias
2 Thermal resistance between the die and the printed circuit board per JEDEC JESD51-8. Board temperature is measured on the top surface of the board near the package.
3 Thermal resistance between the die and the case top surface as measured by the cold plate method (MIL SPEC-883 Method 1012.1).

2.3 Power Considerations

The average chip-junction temperature, $T_J$, in $^\circ$C can be obtained from the following:

$$T_J = T_A + (P_D \times \theta_{JA})$$  \hspace{1cm} (1)

where

$T_A$ = ambient temperature $^\circ$C

$\theta_{JA}$ = package thermal resistance, junction to ambient, $^\circ$C/W

$P_D = P_{INT} + P_{I/O}$

$P_{INT} = I_{DD} \times V_{DD}$ Watts (chip internal power)

$P_{I/O} =$ power dissipation on input and output pins (determined by user)

For most applications $P_{I/O} < 0.3 \times P_{INT}$. If $P_{I/O}$ is neglected, an approximate relationship between $P_D$ and $T_J$ is the following:

$$P_D = K/(T_J + 273 \, ^\circ C)$$  \hspace{1cm} (2)

Solving equations (1) and (2) for $K$ gives:

$$K = P_D \times (T_A + 273 \, ^\circ C) + \theta_{JA} \times P_D^2$$  \hspace{1cm} (3)
where $K$ is a constant pertaining to the particular part. $K$ can be determined from equation (3) by measuring $P_D$ (at equilibrium) for a known $T_A$. Using this value of $K$, the values of $P_D$ and $T_J$ can be obtained by solving equations (1) and (2) iteratively for any value of $T_A$.

### 2.3.1 Layout Practices

Each $V_{CC}$ pin should be provided with a low-impedance path to the board’s power supply. Each ground pin should likewise be provided with a low-impedance path to ground. The power supply pins drive distinct groups of logic on chip. The $V_{CC}$ power supply should be bypassed to ground using at least four 0.1 µF by-pass capacitors located as close as possible to the four sides of the package. The capacitor leads and associated printed circuit traces connecting to chip $V_{CC}$ and ground should be kept to less than half an inch per capacitor lead. A four-layer board is recommended, employing two inner layers as $V_{CC}$ and GND planes.

All output pins on the MPC8250 have fast rise and fall times. Printed circuit (PC) trace interconnection length should be minimized in order to minimize overdamped conditions and reflections caused by these fast output switching times. This recommendation particularly applies to the address and data buses. Maximum PC trace lengths of six inches are recommended. Capacitance calculations should consider all device loads as well as parasitic capacitances due to the PC traces. Attention to proper PCB layout and bypassing becomes especially critical in systems with higher capacitive loads because these loads create higher transient currents in the $V_{CC}$ and GND circuits. Pull up all unused inputs or signals that will be inputs during reset. Special care should be taken to minimize the noise levels on the PLL supply pins.

Table 5 provides preliminary, estimated power dissipation for various configurations. Note that suitable thermal management is required for conditions above $P_D = 3W$ (when the ambient temperature is 70° C or greater) to ensure the junction temperature does not exceed the maximum specified value. Also note that the I/O power should be included when determining whether to use a heat sink.

<table>
<thead>
<tr>
<th>Bus (MHz)</th>
<th>CPM Multiplier</th>
<th>Core CPU Multiplier</th>
<th>CPM (MHz)</th>
<th>CPU (MHz)</th>
<th>$P_{INT} (W)$</th>
<th>$V_{ddl}$ 1.8 Volts</th>
<th>$V_{ddl}$ 2.0 Volts</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td>Nominal</td>
<td>Maximum</td>
<td>Nominal</td>
</tr>
<tr>
<td>66.66</td>
<td>2</td>
<td>3</td>
<td>133</td>
<td>200</td>
<td>1.2</td>
<td>2</td>
<td>1.8</td>
</tr>
<tr>
<td>66.66</td>
<td>2.5</td>
<td>3</td>
<td>166</td>
<td>200</td>
<td>1.3</td>
<td>2.1</td>
<td>1.9</td>
</tr>
<tr>
<td>66.66</td>
<td>3</td>
<td>4</td>
<td>200</td>
<td>266</td>
<td>—</td>
<td>—</td>
<td>2.3</td>
</tr>
<tr>
<td>66.66</td>
<td>3</td>
<td>4.5</td>
<td>200</td>
<td>300</td>
<td>—</td>
<td>—</td>
<td>2.4</td>
</tr>
<tr>
<td>83.33</td>
<td>2</td>
<td>3</td>
<td>166</td>
<td>250</td>
<td>—</td>
<td>—</td>
<td>2.2</td>
</tr>
<tr>
<td>83.33</td>
<td>2</td>
<td>3</td>
<td>166</td>
<td>250</td>
<td>—</td>
<td>—</td>
<td>2.2</td>
</tr>
<tr>
<td>83.33</td>
<td>2.5</td>
<td>3.5</td>
<td>208</td>
<td>291</td>
<td>—</td>
<td>—</td>
<td>2.4</td>
</tr>
</tbody>
</table>

1. Test temperature = room temperature (25° C)
2. $P_{INT} = I_{DD} \times V_{DD}$ Watts
2.4 AC Electrical Characteristics

The following sections include illustrations and tables of clock diagrams, signals, and CPM outputs and inputs for the 66 MHz MPC8250 device. Note that AC timings are based on a 50-pf load. Typical output buffer impedances are shown in Table 6.

Table 6. Output Buffer Impedances

<table>
<thead>
<tr>
<th>Output Buffers</th>
<th>Typical Impedance (Ω)</th>
</tr>
</thead>
<tbody>
<tr>
<td>60x bus</td>
<td>40</td>
</tr>
<tr>
<td>Local bus</td>
<td>40</td>
</tr>
<tr>
<td>Memory controller</td>
<td>40</td>
</tr>
<tr>
<td>Parallel I/O</td>
<td>46</td>
</tr>
<tr>
<td>PCI</td>
<td>25</td>
</tr>
</tbody>
</table>

1 These are typical values at 65° C. The impedance may vary by ±25% with process and temperature.

Table 7 lists CPM output characteristics.

Table 7. AC Characteristics for CPM Outputs

<table>
<thead>
<tr>
<th>Spec Number</th>
<th>Characteristic</th>
<th>Max Delay (ns)</th>
<th>Min Delay (ns)</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td>66 MHz</td>
<td>83 MHz</td>
</tr>
<tr>
<td>sp36a/sp37a</td>
<td>FCC outputs—internal clock (NMSI)</td>
<td>6</td>
<td>5.5</td>
</tr>
<tr>
<td>sp36b/sp37b</td>
<td>FCC outputs—external clock (NMSI)</td>
<td>14</td>
<td>12</td>
</tr>
<tr>
<td>sp40/sp41</td>
<td>TDM outputs/SI</td>
<td>25</td>
<td>16</td>
</tr>
<tr>
<td>sp38a/sp39a</td>
<td>SCC/SMC/SPI/I2C outputs—internal clock (NMSI)</td>
<td>19</td>
<td>16</td>
</tr>
<tr>
<td>sp38b/sp39b</td>
<td>Ex_SCC/SMC/SPI/I2C outputs—external clock (NMSI)</td>
<td>19</td>
<td>16</td>
</tr>
<tr>
<td>sp42/sp43</td>
<td>TIMER/IDMA outputs</td>
<td>14</td>
<td>11</td>
</tr>
<tr>
<td>sp42a/sp43a</td>
<td>PIO outputs</td>
<td>14</td>
<td>11</td>
</tr>
</tbody>
</table>

1 Output specifications are measured from the 50% level of the rising edge of CLKIN to the 50% level of the signal. Timings are measured at the pin.

Table 8 lists CPM input characteristics.

Table 8. AC Characteristics for CPM Inputs

<table>
<thead>
<tr>
<th>Spec Number</th>
<th>Characteristic</th>
<th>Setup (ns)</th>
<th>Hold (ns)</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td>66 MHz</td>
<td>83 MHz</td>
</tr>
<tr>
<td>sp16a/sp17a</td>
<td>FCC inputs—internal clock (NMSI)</td>
<td>10</td>
<td>8</td>
</tr>
<tr>
<td>sp16b/sp17b</td>
<td>FCC inputs—external clock (NMSI)</td>
<td>3</td>
<td>2.5</td>
</tr>
</tbody>
</table>
Table 8. AC Characteristics for CPM Inputs

<table>
<thead>
<tr>
<th>Spec Number</th>
<th>Characteristic</th>
<th>Setup (ns)</th>
<th>Hold (ns)</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td>66 MHz</td>
<td>83 MHz</td>
</tr>
<tr>
<td>sp20 sp21</td>
<td>TDM inputs/SI</td>
<td>15</td>
<td>12</td>
</tr>
<tr>
<td>sp18a sp19a</td>
<td>SCC/SMC/SPI/I2C inputs—internal clock (NMSI)</td>
<td>20</td>
<td>16</td>
</tr>
<tr>
<td>sp18b sp19b</td>
<td>SCC/SMC/SPI/I2C inputs—external clock (NMSI)</td>
<td>5</td>
<td>4</td>
</tr>
<tr>
<td>sp22 sp23</td>
<td>PIO/TIMER/IDMA inputs</td>
<td>10</td>
<td>8</td>
</tr>
</tbody>
</table>

Note: Input specifications are measured from the 50% level of the signal to the 50% level of the rising edge of CLKin. Timings are measured at the pin.

Note that although the specifications generally reference the rising edge of the clock, the following AC timing diagrams also apply when the falling edge is the active edge.

Figure 3 shows the FCC external clock.

![Figure 3. FCC External Clock Diagram](image-url)
Figure 4 shows the FCC internal clock.

Figure 5 shows the SCC/SMC/SPI/I²C external clock.

**Figure 4. FCC Internal Clock Diagram**

**Figure 5. SCC/SMC/SPI/I²C External Clock Diagram**

**Note:** There are four possible timing conditions for SCC and SPI:
1. Input sampled on the rising edge and output driven on the rising edge (shown).
2. Input sampled on the rising edge and output driven on the falling edge.
3. Input sampled on the falling edge and output driven on the falling edge.
4. Input sampled on the falling edge and output driven on the rising edge.
**Figure 6** shows the SCC/SMC/SPI/I2C internal clock.

![SCC/SMC/SPI/I2C Internal Clock Diagram](image)

**Note**: There are four possible timing conditions for SCC and SPI:
1. Input sampled on the rising edge and output driven on the rising edge (shown).
2. Input sampled on the rising edge and output driven on the falling edge.
3. Input sampled on the falling edge and output driven on the falling edge.
4. Input sampled on the falling edge and output driven on the rising edge.

**Figure 6. SCC/SMC/SPI/I2C Internal Clock Diagram**

**Figure 7** shows TDM input and output signals.

![TDM Signal Diagram](image)

**Note**: There are four possible TDM timing conditions:
1. Input sampled on the rising edge and output driven on the rising edge (shown).
2. Input sampled on the rising edge and output driven on the falling edge.
3. Input sampled on the falling edge and output driven on the falling edge.
4. Input sampled on the falling edge and output driven on the rising edge.

**Figure 7. TDM Signal Diagram**
Figure 8 shows PIO, timer, and DMA signals.

Note: TGATE is asserted on the rising edge of the clock; it is deasserted on the falling edge.

**Figure 8. PIO, Timer, and DMA Signal Diagram**

Table 9 lists SIU input characteristics.

**Table 9. AC Characteristics for SIU Inputs**

<table>
<thead>
<tr>
<th>Spec Number</th>
<th>Characteristic</th>
<th>Setup (ns)</th>
<th>Hold (ns)</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td>66 MHz</td>
<td>83 MHz</td>
</tr>
<tr>
<td></td>
<td></td>
<td>66 MHz</td>
<td>83 MHz</td>
</tr>
<tr>
<td>sp11</td>
<td>AACK/ARTRY/TA/TS/TEA(DBG/BG/BR)</td>
<td>6</td>
<td>5</td>
</tr>
<tr>
<td></td>
<td></td>
<td>0.5</td>
<td>0.5</td>
</tr>
<tr>
<td>sp12</td>
<td>Data bus in normal mode</td>
<td>5</td>
<td>4</td>
</tr>
<tr>
<td></td>
<td></td>
<td>0.5</td>
<td>0.5</td>
</tr>
<tr>
<td>sp13</td>
<td>Data bus in ECC and PARITY modes</td>
<td>8</td>
<td>6</td>
</tr>
<tr>
<td></td>
<td></td>
<td>0.5</td>
<td>0.5</td>
</tr>
<tr>
<td>sp14</td>
<td>DP pins</td>
<td>7</td>
<td>6</td>
</tr>
<tr>
<td></td>
<td></td>
<td>0.5</td>
<td>0.5</td>
</tr>
<tr>
<td>sp15</td>
<td>All other pins</td>
<td>5</td>
<td>4</td>
</tr>
<tr>
<td></td>
<td></td>
<td>0.5</td>
<td>0.5</td>
</tr>
</tbody>
</table>

1 Input specifications are measured from the 50% level of the signal to the 50% level of the rising edge of CLkin. Timings are measured at the pin.
Table 10 lists SIU output characteristics.

### Table 10. AC Characteristics for SIU Outputs

<table>
<thead>
<tr>
<th>Spec Number</th>
<th>Characteristic</th>
<th>Max Delay (ns)</th>
<th>Min Delay (ns)</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td>66 MHz</td>
<td>83 MHz</td>
</tr>
<tr>
<td>sp31</td>
<td>PSDVAL/TEA/TA</td>
<td>7</td>
<td>6</td>
</tr>
<tr>
<td>sp32</td>
<td>ADD/ADD_atr./BADDR/Cl/GBL/WT</td>
<td>8</td>
<td>6.5</td>
</tr>
<tr>
<td>sp33a</td>
<td>Data bus</td>
<td>6.5</td>
<td>6.5</td>
</tr>
<tr>
<td>sp33b</td>
<td>DP</td>
<td>8</td>
<td>7</td>
</tr>
<tr>
<td>sp34</td>
<td>Memory controller signals/ALE</td>
<td>6</td>
<td>5</td>
</tr>
<tr>
<td>sp35</td>
<td>All other signals</td>
<td>6</td>
<td>5.5</td>
</tr>
</tbody>
</table>

1. Output specifications are measured from the 50% level of the rising edge of CLKIN to the 50% level of the signal. Timings are measured at the pin.

**NOTE**

Activating data pipelining (setting BRx[DR] in the memory controller) improves the AC timing. When data pipelining is activated, sp12 can be used for data bus setup even when ECC or PARITY are used. Also, sp33a can be used as the AC specification for DP signals.
Figure 9 shows the interaction of several bus signals.

Figure 10 shows signal behavior for all parity modes (including ECC, RMW parity, and standard parity).
**Figure 11** shows signal behavior in MEMC mode.

![MEMC Mode Diagram](image)

**NOTE**

Generally, all MPC8250 bus and system output signals are driven from the rising edge of the input clock (CLKin). Memory controller signals, however, trigger on four points within a CLKin cycle. Each cycle is divided by four internal ticks: T1, T2, T3, and T4. T1 always occurs at the rising edge, and T3 at the falling edge, of CLKin. However, the spacing of T2 and T4 depends on the PLL clock ratio selected, as shown in **Table 11**.

<table>
<thead>
<tr>
<th>PLL Clock Ratio</th>
<th>Tick Spacing (T1 Occurs at the Rising Edge of CLKin)</th>
</tr>
</thead>
<tbody>
<tr>
<td>1:2, 1:3, 1:4, 1:5, 1:6</td>
<td>T2</td>
</tr>
<tr>
<td>1/4 CLKin</td>
<td>1/2 CLKin</td>
</tr>
<tr>
<td>1:2.5</td>
<td>3/10 CLKin</td>
</tr>
<tr>
<td>1:3.5</td>
<td>4/14 CLKin</td>
</tr>
</tbody>
</table>

**Figure 12** is a graphical representation of **Table 11**.

![Internal Tick Spacing for Memory Controller Signals](image)
NOTE
The UPM machine outputs change on the internal tick determined by the memory controller programming; the AC specifications are relative to the internal tick. Note that SDRAM and GPCM machine outputs change on CLKin’s rising edge.

3 Clock Configuration Modes

The MPC8250 has three clocking modes: local, PCI host, and PCI agent. The clocking mode is set according to three input pins—PCI_MODE, PCI_CFG[0], PCI_MODCK—as shown in Table 12.

Table 12. MPC8250 Clocking Modes

<table>
<thead>
<tr>
<th>Pins</th>
<th>Clocking Mode</th>
<th>PCI Clock Frequency Range (MHZ)</th>
<th>Reference</th>
</tr>
</thead>
<tbody>
<tr>
<td>1 — —</td>
<td>Local bus</td>
<td>—</td>
<td>Table 13 and Table 14</td>
</tr>
<tr>
<td>0 0 0</td>
<td>PCI host</td>
<td>50–66</td>
<td>Table 15 and Table 16</td>
</tr>
<tr>
<td>0 0 1</td>
<td>PCI agent</td>
<td>50–66</td>
<td>Table 17 and Table 18</td>
</tr>
</tbody>
</table>

1 Determines PCI clock frequency range. Refer to Section 3.2, “PCI Mode.”

In each clocking mode, the configuration of bus, core, PCI, and CPM frequencies is determined by seven bits during the power-up reset—three hardware configuration pins (MODCK[1–3]) and four bits from hardware configuration word[28–31] (MODCK_H). Both the PLLs and the dividers are set according to the selected MPC8250 clock operation mode as described in the following sections.

NOTE
Clock configurations change only after POR is asserted.

3.1 Local Bus Mode

Table 13 shows the eight basic clock configurations for the MPC8250. Another 49 configurations are available by using the configuration pin (RSTCONF) and driving four pins on the data bus.

Table 13. Clock Default Configurations

<table>
<thead>
<tr>
<th>MODCK[1–3]</th>
<th>Input Clock Frequency</th>
<th>CPM Multiplication Factor</th>
<th>CPM Frequency</th>
<th>Core Multiplication Factor</th>
<th>Core Frequency</th>
</tr>
</thead>
<tbody>
<tr>
<td>000</td>
<td>33 MHz</td>
<td>3</td>
<td>100 MHz</td>
<td>4</td>
<td>133 MHz</td>
</tr>
<tr>
<td>001</td>
<td>33 MHz</td>
<td>3</td>
<td>100 MHz</td>
<td>5</td>
<td>166 MHz</td>
</tr>
<tr>
<td>010</td>
<td>33 MHz</td>
<td>4</td>
<td>133 MHz</td>
<td>4</td>
<td>133 MHz</td>
</tr>
<tr>
<td>011</td>
<td>33 MHz</td>
<td>4</td>
<td>133 MHz</td>
<td>5</td>
<td>166 MHz</td>
</tr>
</tbody>
</table>
Table 14 describes all possible clock configurations when using the hard reset configuration sequence. Note also that basic modes are shown in **boldface** type. The frequencies listed are for the purpose of illustration only. Users must select a mode and input bus frequency so that the resulting configuration does not exceed the frequency rating of the user’s device.

**Table 14. Clock Configuration Modes**

<table>
<thead>
<tr>
<th>MODCK[1–3]</th>
<th>Input Clock Frequency</th>
<th>CPM Multiplication Factor</th>
<th>CPM Frequency</th>
<th>Core Multiplication Factor</th>
<th>Core Frequency</th>
</tr>
</thead>
<tbody>
<tr>
<td>100</td>
<td>66 MHz</td>
<td>2</td>
<td>133 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
</tr>
<tr>
<td>101</td>
<td>66 MHz</td>
<td>2</td>
<td>133 MHz</td>
<td>3</td>
<td>200 MHz</td>
</tr>
<tr>
<td>110</td>
<td>66 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
</tr>
<tr>
<td>111</td>
<td>66 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>3</td>
<td>200 MHz</td>
</tr>
</tbody>
</table>

**Table 13. Clock Default Configurations**

<table>
<thead>
<tr>
<th>MODCK[1–3]</th>
<th>Input Clock Frequency</th>
<th>CPM Multiplication Factor</th>
<th>CPM Frequency</th>
<th>Core Multiplication Factor</th>
<th>Core Frequency</th>
</tr>
</thead>
<tbody>
<tr>
<td>0001_000</td>
<td>33 MHz</td>
<td>2</td>
<td>66 MHz</td>
<td>4</td>
<td>133 MHz</td>
</tr>
<tr>
<td>0001_001</td>
<td>33 MHz</td>
<td>2</td>
<td>66 MHz</td>
<td>5</td>
<td>166 MHz</td>
</tr>
<tr>
<td>0001_010</td>
<td>33 MHz</td>
<td>2</td>
<td>66 MHz</td>
<td>6</td>
<td>200 MHz</td>
</tr>
<tr>
<td>0001_011</td>
<td>33 MHz</td>
<td>2</td>
<td>66 MHz</td>
<td>7</td>
<td>233 MHz</td>
</tr>
<tr>
<td>0001_100</td>
<td>33 MHz</td>
<td>2</td>
<td>66 MHz</td>
<td>8</td>
<td>266 MHz</td>
</tr>
<tr>
<td>0001_101</td>
<td>33 MHz</td>
<td>3</td>
<td>100 MHz</td>
<td>4</td>
<td>133 MHz</td>
</tr>
<tr>
<td>0001_110</td>
<td>33 MHz</td>
<td>3</td>
<td>100 MHz</td>
<td>5</td>
<td>166 MHz</td>
</tr>
<tr>
<td>0001_111</td>
<td>33 MHz</td>
<td>3</td>
<td>100 MHz</td>
<td>6</td>
<td>200 MHz</td>
</tr>
<tr>
<td>0010_000</td>
<td>33 MHz</td>
<td>3</td>
<td>100 MHz</td>
<td>7</td>
<td>233 MHz</td>
</tr>
<tr>
<td>0010_001</td>
<td>33 MHz</td>
<td>3</td>
<td>100 MHz</td>
<td>8</td>
<td>266 MHz</td>
</tr>
<tr>
<td>0010_010</td>
<td>33 MHz</td>
<td>4</td>
<td>133 MHz</td>
<td>4</td>
<td>133 MHz</td>
</tr>
<tr>
<td>0010_011</td>
<td>33 MHz</td>
<td>4</td>
<td>133 MHz</td>
<td>5</td>
<td>166 MHz</td>
</tr>
<tr>
<td>0010_100</td>
<td>33 MHz</td>
<td>4</td>
<td>133 MHz</td>
<td>6</td>
<td>200 MHz</td>
</tr>
<tr>
<td>0010_101</td>
<td>33 MHz</td>
<td>4</td>
<td>133 MHz</td>
<td>7</td>
<td>233 MHz</td>
</tr>
<tr>
<td>0010_110</td>
<td>33 MHz</td>
<td>4</td>
<td>133 MHz</td>
<td>8</td>
<td>266 MHz</td>
</tr>
<tr>
<td>0010_111</td>
<td>33 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>4</td>
<td>133 MHz</td>
</tr>
<tr>
<td>0011_000</td>
<td>33 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>5</td>
<td>166 MHz</td>
</tr>
<tr>
<td>0011_001</td>
<td>33 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>6</td>
<td>200 MHz</td>
</tr>
<tr>
<td>0011_010</td>
<td>33 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>7</td>
<td>233 MHz</td>
</tr>
<tr>
<td>0011_011</td>
<td>33 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>8</td>
<td>266 MHz</td>
</tr>
</tbody>
</table>

MPC8250 Hardware Specifications, Rev. 2

Freescale Semiconductor
Table 14. Clock Configuration Modes ¹ (continued)

<table>
<thead>
<tr>
<th>MODCK_H–MODCK[1–3]</th>
<th>Input Clock Frequency²,³</th>
<th>CPM Multiplication Factor²</th>
<th>CPM Frequency²</th>
<th>Core Multiplication Factor²</th>
<th>Core Frequency²</th>
</tr>
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<tbody>
<tr>
<td>0011_100</td>
<td>33 MHz</td>
<td>6</td>
<td>200 MHz</td>
<td>4</td>
<td>133 MHz</td>
</tr>
<tr>
<td>0011_101</td>
<td>33 MHz</td>
<td>6</td>
<td>200 MHz</td>
<td>5</td>
<td>166 MHz</td>
</tr>
<tr>
<td>0011_110</td>
<td>33 MHz</td>
<td>6</td>
<td>200 MHz</td>
<td>6</td>
<td>200 MHz</td>
</tr>
<tr>
<td>0011_111</td>
<td>33 MHz</td>
<td>6</td>
<td>200 MHz</td>
<td>7</td>
<td>233 MHz</td>
</tr>
<tr>
<td>0100_000</td>
<td>33 MHz</td>
<td>6</td>
<td>200 MHz</td>
<td>8</td>
<td>266 MHz</td>
</tr>
<tr>
<td>0100_001</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td>Reserved</td>
</tr>
<tr>
<td>0100_010</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
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<td>0100_011</td>
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<td>0100_100</td>
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<td></td>
<td></td>
</tr>
<tr>
<td>0100_101</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>0100_110</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
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<td>Reserved</td>
</tr>
<tr>
<td>0101_000</td>
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<tr>
<td>0101_011</td>
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<td></td>
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<td>0101_100</td>
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<td></td>
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<tr>
<td>0101_101</td>
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<td>133 MHz</td>
<td>2</td>
<td>133 MHz</td>
</tr>
<tr>
<td>0101_110</td>
<td>66 MHz</td>
<td>2</td>
<td>133 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
</tr>
<tr>
<td>0101_111</td>
<td>66 MHz</td>
<td>2</td>
<td>133 MHz</td>
<td>3</td>
<td>200 MHz</td>
</tr>
<tr>
<td>0110_000</td>
<td>66 MHz</td>
<td>2</td>
<td>133 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
</tr>
<tr>
<td>0110_001</td>
<td>66 MHz</td>
<td>2</td>
<td>133 MHz</td>
<td>4</td>
<td>266 MHz</td>
</tr>
<tr>
<td>0110_010</td>
<td>66 MHz</td>
<td>2</td>
<td>133 MHz</td>
<td>4.5</td>
<td>300 MHz</td>
</tr>
<tr>
<td>0110_011</td>
<td>66 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>2</td>
<td>133 MHz</td>
</tr>
<tr>
<td>0110_100</td>
<td>66 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
</tr>
<tr>
<td>0110_101</td>
<td>66 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>3</td>
<td>200 MHz</td>
</tr>
<tr>
<td>0110_110</td>
<td>66 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
</tr>
<tr>
<td>0110_111</td>
<td>66 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>4</td>
<td>266 MHz</td>
</tr>
<tr>
<td>0111_000</td>
<td>66 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>4.5</td>
<td>300 MHz</td>
</tr>
</tbody>
</table>
Table 14. Clock Configuration Modes \(^1\) (continued)

<table>
<thead>
<tr>
<th>MODCK_H–MODCK[1–3]</th>
<th>Input Clock Frequency(^1,2,3)</th>
<th>CPM Multiplication Factor(^2)</th>
<th>CPM Frequency(^2)</th>
<th>Core Multiplication Factor(^2)</th>
<th>Core Frequency(^2)</th>
</tr>
</thead>
<tbody>
<tr>
<td>0111_001</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>2</td>
<td>133 MHz</td>
</tr>
<tr>
<td>0111_010</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
</tr>
<tr>
<td>0111_011</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>3</td>
<td>200 MHz</td>
</tr>
<tr>
<td>0111_100</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
</tr>
<tr>
<td>0111_101</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>4</td>
<td>266 MHz</td>
</tr>
<tr>
<td>0111_110</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>4.5</td>
<td>300 MHz</td>
</tr>
<tr>
<td>0111_111</td>
<td>66 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>2</td>
<td>133 MHz</td>
</tr>
<tr>
<td>1000_000</td>
<td>66 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
</tr>
<tr>
<td>1000_001</td>
<td>66 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>3</td>
<td>200 MHz</td>
</tr>
<tr>
<td>1000_010</td>
<td>66 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
</tr>
<tr>
<td>1000_011</td>
<td>66 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>4</td>
<td>266 MHz</td>
</tr>
<tr>
<td>1000_100</td>
<td>66 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>4.5</td>
<td>300 MHz</td>
</tr>
</tbody>
</table>

\(^1\) Because of speed dependencies, not all of the possible configurations in Table 14 are applicable.

\(^2\) The user should choose the input clock frequency and the multiplication factors such that the frequency of the CPU is equal to or greater than 133 MHz (150 MHz for extended temperature parts) and the CPM ranges between 66–233 MHz.

\(^3\) Input clock frequency is given only for the purpose of reference. User should set MODCK_H–MODCK_L so that the resulting configuration does not exceed the frequency rating of the user’s part.

### 3.2 PCI Mode

The PCI mode is selected according to three input pins, as shown in Table 12. In addition, note the following:

**NOTE: PCI_MODCK**

In PCI mode only, PCI_MODCK comes from the LGPL5 pin and MODCK_H[0–3] comes from \{LGPL0, LGPL1, LGPL2, LGPL3\}.

**NOTE: Tval (Output Hold)**

The minimum Tval = 2 when PCI_MODCK = 1, and the minimum Tval = 1 when PCI_MODCK = 0. Therefore, designers should use clock configurations that fit this condition to achieve PCI-compliant AC timing.

**NOTE**

Clock configurations change only after POR is asserted.
3.2.1 PCI Host Mode

The frequencies listed in Table 15 are for the purpose of illustration only. Users must select a mode and input bus frequency so that the resulting configuration does not exceed the frequency rating of the user’s device.

Table 15. Clock Default Configurations in PCI Host Mode (MODCK_HI = 0000)

<table>
<thead>
<tr>
<th>MODCK[1–3]1</th>
<th>Input Clock Frequency (Bus)</th>
<th>CPM Multiplication Factor</th>
<th>CPM Frequency</th>
<th>Core Multiplication Factor</th>
<th>Core Frequency</th>
<th>PCI Division Factor 2</th>
<th>PCI Frequency2</th>
</tr>
</thead>
<tbody>
<tr>
<td>000</td>
<td>66 MHz</td>
<td>2</td>
<td>133 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>2/4</td>
<td>66/33 MHz</td>
</tr>
<tr>
<td>001</td>
<td>66 MHz</td>
<td>2</td>
<td>133 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>2/4</td>
<td>66/33 MHz</td>
</tr>
<tr>
<td>010</td>
<td>66 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>3/6</td>
<td>55/28 MHz</td>
</tr>
<tr>
<td>011</td>
<td>66 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>3/6</td>
<td>55/28 MHz</td>
</tr>
<tr>
<td>100</td>
<td>66 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>4</td>
<td>266 MHz</td>
<td>3/6</td>
<td>55/28 MHz</td>
</tr>
<tr>
<td>101</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>3/6</td>
<td>66/33 MHz</td>
</tr>
<tr>
<td>110</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>3/6</td>
<td>66/33 MHz</td>
</tr>
<tr>
<td>111</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>4</td>
<td>266 MHz</td>
<td>3/6</td>
<td>66/33 MHz</td>
</tr>
</tbody>
</table>

1 Assumes MODCK_HI = 0000.
2 The frequency depends on the value of PCI_MODCK. If PCI_MODCK is high (logic ‘1’), the PCI frequency is divided by 2 (33 instead of 66 MHz, etc.) Refer to Table 12.

Table 16 describes all possible clock configurations when using the MPC8250’s internal PCI bridge in host mode.

Table 16. Clock Configuration Modes in PCI Host Mode

<table>
<thead>
<tr>
<th>MODCK_H - MODCK[1–3]</th>
<th>Input Clock Frequency 1 (Bus)</th>
<th>CPM Multiplication Factor</th>
<th>CPM Frequency</th>
<th>Core Multiplication Factor</th>
<th>Core Frequency</th>
<th>PCI Division Factor 2</th>
<th>PCI Frequency2</th>
</tr>
</thead>
<tbody>
<tr>
<td>0001_000</td>
<td>33 MHz</td>
<td>3</td>
<td>100 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>3/6</td>
<td>33/16 MHz</td>
</tr>
<tr>
<td>0001_001</td>
<td>33 MHz</td>
<td>3</td>
<td>100 MHz</td>
<td>6</td>
<td>200 MHz</td>
<td>3/6</td>
<td>33/16 MHz</td>
</tr>
<tr>
<td>0001_010</td>
<td>33 MHz</td>
<td>3</td>
<td>100 MHz</td>
<td>7</td>
<td>233 MHz</td>
<td>3/6</td>
<td>33/16 MHz</td>
</tr>
<tr>
<td>0001_011</td>
<td>33 MHz</td>
<td>3</td>
<td>100 MHz</td>
<td>8</td>
<td>266 MHz</td>
<td>3/6</td>
<td>33/16 MHz</td>
</tr>
<tr>
<td>0010_000</td>
<td>33 MHz</td>
<td>4</td>
<td>133 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>4/8</td>
<td>33/16 MHz</td>
</tr>
<tr>
<td>0010_001</td>
<td>33 MHz</td>
<td>4</td>
<td>133 MHz</td>
<td>6</td>
<td>200 MHz</td>
<td>4/8</td>
<td>33/16 MHz</td>
</tr>
<tr>
<td>0010_010</td>
<td>33 MHz</td>
<td>4</td>
<td>133 MHz</td>
<td>7</td>
<td>233 MHz</td>
<td>4/8</td>
<td>33/16 MHz</td>
</tr>
<tr>
<td>0010_011</td>
<td>33 MHz</td>
<td>4</td>
<td>133 MHz</td>
<td>8</td>
<td>266 MHz</td>
<td>4/8</td>
<td>33/16 MHz</td>
</tr>
<tr>
<td>0011_000</td>
<td>33 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>5</td>
<td>33 MHz</td>
</tr>
<tr>
<td>0011_001</td>
<td>33 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>6</td>
<td>200 MHz</td>
<td>5</td>
<td>33 MHz</td>
</tr>
</tbody>
</table>
Table 16. Clock Configuration Modes in PCI Host Mode (continued)

<table>
<thead>
<tr>
<th>MODCK_H – MODCK[1–3]</th>
<th>Input Clock Frequency (Bus)</th>
<th>CPM Multiplication Factor</th>
<th>CPM Frequency</th>
<th>CPM Multiplication Factor</th>
<th>Core Frequency</th>
<th>PCI Division Factor</th>
<th>PCI Frequency</th>
</tr>
</thead>
<tbody>
<tr>
<td>0011_010³</td>
<td>33 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>7</td>
<td>233 MHz</td>
<td>5</td>
<td>33 MHz</td>
</tr>
<tr>
<td>0011_011³</td>
<td>33 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>8</td>
<td>266 MHz</td>
<td>5</td>
<td>33 MHz</td>
</tr>
<tr>
<td>0100_000³</td>
<td>33 MHz</td>
<td>6</td>
<td>200 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>6</td>
<td>33 MHz</td>
</tr>
<tr>
<td>0100_001³</td>
<td>33 MHz</td>
<td>6</td>
<td>200 MHz</td>
<td>6</td>
<td>200 MHz</td>
<td>6</td>
<td>33 MHz</td>
</tr>
<tr>
<td>0100_010³</td>
<td>33 MHz</td>
<td>6</td>
<td>200 MHz</td>
<td>7</td>
<td>233 MHz</td>
<td>6</td>
<td>33 MHz</td>
</tr>
<tr>
<td>0100_011³</td>
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<td>6</td>
<td>200 MHz</td>
<td>8</td>
<td>266 MHz</td>
<td>6</td>
<td>33 MHz</td>
</tr>
<tr>
<td>0101_000</td>
<td>66 MHz</td>
<td>2</td>
<td>133 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>2/4</td>
<td>66/33 MHz</td>
</tr>
<tr>
<td>0101_001</td>
<td>66 MHz</td>
<td>2</td>
<td>133 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>2/4</td>
<td>66/33 MHz</td>
</tr>
<tr>
<td>0101_010</td>
<td>66 MHz</td>
<td>2</td>
<td>133 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>2/4</td>
<td>66/33 MHz</td>
</tr>
<tr>
<td>0101_011</td>
<td>66 MHz</td>
<td>2</td>
<td>133 MHz</td>
<td>4</td>
<td>266 MHz</td>
<td>2/4</td>
<td>66/33 MHz</td>
</tr>
<tr>
<td>0101_100</td>
<td>66 MHz</td>
<td>2</td>
<td>133 MHz</td>
<td>4.5</td>
<td>300 MHz</td>
<td>2/4</td>
<td>66/33 MHz</td>
</tr>
<tr>
<td>0110_000</td>
<td>66 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>3/6</td>
<td>55/28 MHz</td>
</tr>
<tr>
<td>0110_001</td>
<td>66 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>3/6</td>
<td>55/28 MHz</td>
</tr>
<tr>
<td>0110_010</td>
<td>66 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>3/6</td>
<td>55/28 MHz</td>
</tr>
<tr>
<td>0110_011</td>
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<td>2.5</td>
<td>166 MHz</td>
<td>4</td>
<td>266 MHz</td>
<td>3/6</td>
<td>55/28 MHz</td>
</tr>
<tr>
<td>0110_100</td>
<td>66 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>4.5</td>
<td>300 MHz</td>
<td>3/6</td>
<td>55/28 MHz</td>
</tr>
<tr>
<td>0111_000</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>3/6</td>
<td>66/33 MHz</td>
</tr>
<tr>
<td>0111_001</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>3/6</td>
<td>66/33 MHz</td>
</tr>
<tr>
<td>0111_010</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>3/6</td>
<td>66/33 MHz</td>
</tr>
<tr>
<td>0111_011</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>4</td>
<td>266 MHz</td>
<td>3/6</td>
<td>66/33 MHz</td>
</tr>
<tr>
<td>0111_100</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>4.5</td>
<td>300 MHz</td>
<td>3/6</td>
<td>66/33 MHz</td>
</tr>
<tr>
<td>1000_000</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>4/8</td>
<td>50/25 MHz</td>
</tr>
<tr>
<td>1000_001</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>4/8</td>
<td>50/25 MHz</td>
</tr>
<tr>
<td>1000_010</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>4/8</td>
<td>50/25 MHz</td>
</tr>
<tr>
<td>1000_011</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>4</td>
<td>266 MHz</td>
<td>4/8</td>
<td>50/25 MHz</td>
</tr>
<tr>
<td>1000_100</td>
<td>66 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>4.5</td>
<td>300 MHz</td>
<td>4/8</td>
<td>50/25 MHz</td>
</tr>
<tr>
<td>1001_000</td>
<td>66 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>4/8</td>
<td>58/29 MHz</td>
</tr>
</tbody>
</table>
3.2.2 PCI Agent Mode

The frequencies listed in Table 17 are for the purpose of illustration only. Users must select a mode and input bus frequency so that the resulting configuration does not exceed the frequency rating of the user’s device.

Table 17. Clock Default Configurations in PCI Agent Mode (MODCK_HI = 0000)

<table>
<thead>
<tr>
<th>MODCK[1–3]</th>
<th>Input Clock Frequency (PCI)</th>
<th>CPM Multiplication Factor</th>
<th>CPM Frequency</th>
<th>Core Multiplication Factor</th>
<th>Core Frequency</th>
<th>Bus Division Factor</th>
<th>60x Bus Frequency</th>
</tr>
</thead>
<tbody>
<tr>
<td>000</td>
<td>66/33 MHz</td>
<td>2/4</td>
<td>133 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>2</td>
<td>66 MHz</td>
</tr>
<tr>
<td>001</td>
<td>66/33 MHz</td>
<td>2/4</td>
<td>133 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>2</td>
<td>66 MHz</td>
</tr>
<tr>
<td>010</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>200 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>3</td>
<td>66 MHz</td>
</tr>
<tr>
<td>011</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>200 MHz</td>
<td>4</td>
<td>266 MHz</td>
<td>3</td>
<td>66 MHz</td>
</tr>
</tbody>
</table>
Table 18 describes all possible clock configurations when using the MPC8250’s internal PCI bridge in agent mode.

Table 18. Clock Configuration Modes in PCI Agent Mode

<table>
<thead>
<tr>
<th>MODCK[1–3]1</th>
<th>Input Clock Frequency (PCI)2</th>
<th>CPM Multiplication Factor 2</th>
<th>CPM Frequency</th>
<th>Core Multiplication Factor</th>
<th>Core Frequency 3</th>
<th>Bus Division Factor</th>
<th>60x Bus Frequency4</th>
</tr>
</thead>
<tbody>
<tr>
<td>100</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>200 MHz</td>
<td>3</td>
<td>240 MHz</td>
<td>2.5</td>
<td>80 MHz</td>
</tr>
<tr>
<td>101</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>200 MHz</td>
<td>3.5</td>
<td>280 MHz</td>
<td>2.5</td>
<td>80 MHz</td>
</tr>
<tr>
<td>110</td>
<td>66/33 MHz</td>
<td>4/8</td>
<td>266 MHz</td>
<td>3.5</td>
<td>300 MHz</td>
<td>3</td>
<td>88 MHz</td>
</tr>
<tr>
<td>111</td>
<td>66/33 MHz</td>
<td>4/8</td>
<td>266 MHz</td>
<td>3</td>
<td>300 MHz</td>
<td>2.5</td>
<td>100 MHz</td>
</tr>
</tbody>
</table>

1 Assumes MODCK_HI = 0000.
2 The frequency depends on the value of PCI_MODCK. If PCI_MODCK is high (logic ‘1’), the PCI frequency is divided by 2 (33 instead of 66 MHz, etc.) and the CPM multiplication factor is multiplied by 2. Refer to Table 12.
3 Core frequency = (60x bus frequency)(core multiplication factor)
4 Bus frequency = CPM frequency / bus division factor

Table 17. Clock Default Configurations in PCI Agent Mode (MODCK_HI = 0000)

<table>
<thead>
<tr>
<th>MODCK_H = MODCK[1–3]</th>
<th>Input Clock Frequency (PCI)1, 2</th>
<th>CPM Multiplication Factor1</th>
<th>CPM Frequency</th>
<th>Core Multiplication Factor</th>
<th>Core Frequency3</th>
<th>Bus Division Factor</th>
<th>60x Bus Frequency4</th>
</tr>
</thead>
<tbody>
<tr>
<td>0001_000</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>133 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>4</td>
<td>33 MHz</td>
</tr>
<tr>
<td>0001_010</td>
<td>66/33 MHz</td>
<td>2/4</td>
<td>133 MHz</td>
<td>6</td>
<td>200 MHz</td>
<td>4</td>
<td>33 MHz</td>
</tr>
<tr>
<td>0001_011</td>
<td>66/33 MHz</td>
<td>2/4</td>
<td>133 MHz</td>
<td>7</td>
<td>233 MHz</td>
<td>4</td>
<td>33 MHz</td>
</tr>
<tr>
<td>0001_100</td>
<td>66/33 MHz</td>
<td>2/4</td>
<td>133 MHz</td>
<td>8</td>
<td>266 MHz</td>
<td>4</td>
<td>33 MHz</td>
</tr>
<tr>
<td>0010_001</td>
<td>50/25 MHz</td>
<td>3/6</td>
<td>150 MHz</td>
<td>3</td>
<td>180 MHz</td>
<td>2.5</td>
<td>60 MHz</td>
</tr>
<tr>
<td>0010_010</td>
<td>50/25 MHz</td>
<td>3/6</td>
<td>150 MHz</td>
<td>3.5</td>
<td>210 MHz</td>
<td>2.5</td>
<td>60 MHz</td>
</tr>
<tr>
<td>0010_011</td>
<td>50/25 MHz</td>
<td>3/6</td>
<td>150 MHz</td>
<td>4</td>
<td>240 MHz</td>
<td>2.5</td>
<td>60 MHz</td>
</tr>
<tr>
<td>0010_100</td>
<td>50/25 MHz</td>
<td>3/6</td>
<td>150 MHz</td>
<td>4.5</td>
<td>270 MHz</td>
<td>2.5</td>
<td>60 MHz</td>
</tr>
<tr>
<td>0011_000</td>
<td>66/33 MHz</td>
<td>2/4</td>
<td>133 MHz</td>
<td>2.5</td>
<td>110 MHz</td>
<td>3</td>
<td>44 MHz</td>
</tr>
<tr>
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<td>66/33 MHz</td>
<td>2/4</td>
<td>133 MHz</td>
<td>3</td>
<td>132 MHz</td>
<td>3</td>
<td>44 MHz</td>
</tr>
<tr>
<td>0011_010</td>
<td>66/33 MHz</td>
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<td>44 MHz</td>
</tr>
<tr>
<td>0011_011</td>
<td>66/33 MHz</td>
<td>2/4</td>
<td>133 MHz</td>
<td>4</td>
<td>176 MHz</td>
<td>3</td>
<td>44 MHz</td>
</tr>
<tr>
<td>0011_100</td>
<td>66/33 MHz</td>
<td>2/4</td>
<td>133 MHz</td>
<td>4.5</td>
<td>198 MHz</td>
<td>3</td>
<td>44 MHz</td>
</tr>
<tr>
<td>0100_000</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>200 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>3</td>
<td>66 MHz</td>
</tr>
<tr>
<td>0100_001</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>200 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>3</td>
<td>66 MHz</td>
</tr>
<tr>
<td>0100_010</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>200 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>3</td>
<td>66 MHz</td>
</tr>
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</table>

MPC8250 Hardware Specifications, Rev. 2
### Table 18. Clock Configuration Modes in PCI Agent Mode (continued)

<table>
<thead>
<tr>
<th>MODCK_H - MODCK[1–3]</th>
<th>Input Clock Frequency (PCI)</th>
<th>CPM Multiplication Factor¹</th>
<th>CPM Frequency</th>
<th>Core Multiplication Factor</th>
<th>Core Frequency³</th>
<th>Bus Division Factor</th>
<th>60x Bus Frequency¹⁴</th>
</tr>
</thead>
<tbody>
<tr>
<td>0100_011</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>200 MHz</td>
<td>4</td>
<td>266 MHz</td>
<td>3</td>
<td>66 MHz</td>
</tr>
<tr>
<td>0100_100</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>200 MHz</td>
<td>4.5</td>
<td>300 MHz</td>
<td>3</td>
<td>66 MHz</td>
</tr>
<tr>
<td>0101_000⁵</td>
<td>33 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>2.5</td>
<td>66 MHz</td>
</tr>
<tr>
<td>0101_001⁵</td>
<td>33 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>2.5</td>
<td>66 MHz</td>
</tr>
<tr>
<td>0101_010⁵</td>
<td>33 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>2.5</td>
<td>66 MHz</td>
</tr>
<tr>
<td>0101_011⁵</td>
<td>33 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>4</td>
<td>266 MHz</td>
<td>2.5</td>
<td>66 MHz</td>
</tr>
<tr>
<td>0101_100⁵</td>
<td>33 MHz</td>
<td>5</td>
<td>166 MHz</td>
<td>4.5</td>
<td>300 MHz</td>
<td>2.5</td>
<td>66 MHz</td>
</tr>
<tr>
<td>0110_000</td>
<td>50/25 MHz</td>
<td>4/8</td>
<td>200 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
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<td>66 MHz</td>
</tr>
<tr>
<td>0110_001</td>
<td>50/25 MHz</td>
<td>4/8</td>
<td>200 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>3</td>
<td>66 MHz</td>
</tr>
<tr>
<td>0110_010</td>
<td>50/25 MHz</td>
<td>4/8</td>
<td>200 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>3</td>
<td>66 MHz</td>
</tr>
<tr>
<td>0110_011</td>
<td>50/25 MHz</td>
<td>4/8</td>
<td>200 MHz</td>
<td>4</td>
<td>266 MHz</td>
<td>3</td>
<td>66 MHz</td>
</tr>
<tr>
<td>0110_100</td>
<td>50/25 MHz</td>
<td>4/8</td>
<td>200 MHz</td>
<td>4.5</td>
<td>300 MHz</td>
<td>3</td>
<td>66 MHz</td>
</tr>
<tr>
<td>0111_000</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>200 MHz</td>
<td>2</td>
<td>200 MHz</td>
<td>2</td>
<td>100 MHz</td>
</tr>
<tr>
<td>0111_001</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>200 MHz</td>
<td>2.5</td>
<td>250 MHz</td>
<td>2</td>
<td>100 MHz</td>
</tr>
<tr>
<td>0111_010</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>200 MHz</td>
<td>3</td>
<td>300 MHz</td>
<td>2</td>
<td>100 MHz</td>
</tr>
<tr>
<td>0111_011</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>200 MHz</td>
<td>3.5</td>
<td>350 MHz</td>
<td>2</td>
<td>100 MHz</td>
</tr>
<tr>
<td>1000_000</td>
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<td>3/6</td>
<td>200 MHz</td>
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<td>160 MHz</td>
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<td>80 MHz</td>
</tr>
<tr>
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<td>3/6</td>
<td>200 MHz</td>
<td>2.5</td>
<td>200 MHz</td>
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<td>80 MHz</td>
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<tr>
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<td>200 MHz</td>
<td>3</td>
<td>240 MHz</td>
<td>2.5</td>
<td>80 MHz</td>
</tr>
<tr>
<td>1000_011</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>200 MHz</td>
<td>3.5</td>
<td>280 MHz</td>
<td>2.5</td>
<td>80 MHz</td>
</tr>
<tr>
<td>1000_100</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>200 MHz</td>
<td>4</td>
<td>320 MHz</td>
<td>2.5</td>
<td>80 MHz</td>
</tr>
<tr>
<td>1000_101</td>
<td>66/33 MHz</td>
<td>3/6</td>
<td>200 MHz</td>
<td>4.5</td>
<td>360 MHz</td>
<td>2.5</td>
<td>80 MHz</td>
</tr>
<tr>
<td>1001_000</td>
<td>66/33 MHz</td>
<td>4/8</td>
<td>266 MHz</td>
<td>2.5</td>
<td>166 MHz</td>
<td>4</td>
<td>66 MHz</td>
</tr>
<tr>
<td>1001_001</td>
<td>66/33 MHz</td>
<td>4/8</td>
<td>266 MHz</td>
<td>3</td>
<td>200 MHz</td>
<td>4</td>
<td>66 MHz</td>
</tr>
<tr>
<td>1001_010</td>
<td>66/33 MHz</td>
<td>4/8</td>
<td>266 MHz</td>
<td>3.5</td>
<td>233 MHz</td>
<td>4</td>
<td>66 MHz</td>
</tr>
<tr>
<td>1001_011</td>
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<td>4/8</td>
<td>266 MHz</td>
<td>4</td>
<td>266 MHz</td>
<td>4</td>
<td>66 MHz</td>
</tr>
<tr>
<td>1001_100</td>
<td>66/33 MHz</td>
<td>4/8</td>
<td>266 MHz</td>
<td>4.5</td>
<td>300 MHz</td>
<td>4</td>
<td>66 MHz</td>
</tr>
</tbody>
</table>
4 Pinout

This section provides the pin assignments and pinout list for the MPC8250.

4.1 TBGA Package

The following figures and table represent the standard 480 TBGA package. For information on the alternate package, refer to Section 4.2, “PBGA Package.”
4.1.1 TBGA Pin Assignments

Figure 13 shows the pinout of the TBGA package as viewed from the top surface.

Figure 13. Pinout of the 480 TBGA Package as Viewed from the Top Surface
Figure 14 shows the side profile of the TBGA package to indicate the direction of the top surface view.

Table 20 shows the pinout list of the TBGA package of the MPC8250. Table 19 defines the conventions and acronyms used in Table 20.

Table 19. Symbol Legend

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Meaning</th>
</tr>
</thead>
<tbody>
<tr>
<td>OVERBAR</td>
<td>Signals with overbars, such as TA, are active low.</td>
</tr>
<tr>
<td>MII</td>
<td>Indicates that a signal is part of the media independent interface.</td>
</tr>
</tbody>
</table>

Table 20. MPC8250 TBGA Package Pinout List

<table>
<thead>
<tr>
<th>Pin Name</th>
<th>Ball</th>
</tr>
</thead>
<tbody>
<tr>
<td>BR</td>
<td>W5</td>
</tr>
<tr>
<td>BG</td>
<td>F4</td>
</tr>
<tr>
<td>ABB/IRQ2</td>
<td>E2</td>
</tr>
<tr>
<td>TS</td>
<td>E3</td>
</tr>
<tr>
<td>A0</td>
<td>G1</td>
</tr>
<tr>
<td>A1</td>
<td>H5</td>
</tr>
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<td>A2</td>
<td>H2</td>
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<td>J3</td>
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<td>A7</td>
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<td>K1</td>
</tr>
<tr>
<td>Pin Name</td>
<td>Ball</td>
</tr>
<tr>
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<td>--------</td>
</tr>
<tr>
<td>A13</td>
<td>L5</td>
</tr>
<tr>
<td>A14</td>
<td>L4</td>
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<td>A15</td>
<td>L3</td>
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<td>A16</td>
<td>L2</td>
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## Table 20. MPC8250 TBGA Package Pinout List (continued)

<table>
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<th>Ball</th>
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<tr>
<td>D3</td>
<td>A13</td>
</tr>
<tr>
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<td>D14</td>
<td>B7</td>
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<td>D16</td>
<td>D19</td>
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<td>D17</td>
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<td>D18</td>
<td>D15</td>
</tr>
<tr>
<td>D19</td>
<td>C13</td>
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<tr>
<td>D20</td>
<td>B11</td>
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## Table 20. MPC8250 TBGA Package Pinout List (continued)

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Table 20. MPC8250 TBGA Package Pinout List (continued)

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MPC8250 Hardware Specifications, Rev. 2
Table 20. MPC8250 TBGA Package Pinout List (continued)

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Table 20. MPC8250 TBGA Package Pinout List (continued)

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</tbody>
</table>

1 The default configuration of the CPM pins (PA[0–31], PB[4–31], PC[0–31], PD[4–31]) is input. To prevent excessive DC current, it is recommended to either pull unused pins to GND or VDDH, or to configure them as outputs.

2 Must be pulled down or left floating.

3 If PCI is not desired, this pin should be pulled up or left floating.

4 For information on how to use this pin, refer to MPC8260 PowerQUICC II Thermal Resistor Guide (AN2271/D) available at www.freescale.com.

## 4.2 PBGA Package

The following figures and table represent the alternate 516 PBGA package. For information on the standard package for the MPC8250, refer to Section 4.1, “TBGA Package.”
### 4.2.1 PBGA Pin Assignments

Figure 15 shows the pinout of the PBGA package as viewed from the top surface.

![Pinout of the 516 PBGA Package (View from Top)](image)

**Figure 15. Pinout of the 516 PBGA Package (View from Top)**
Figure 16 shows the side profile of the PBGA package to indicate the direction of the top surface view.

Table 21 shows the pinout list of the PBGA package of the MPC8250. Table 21 defines conventions and acronyms used in Table 22.

### Table 21. Symbol Legend

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Meaning</th>
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<tbody>
<tr>
<td>OVERBAR</td>
<td>Signals with overbars, such as TA, are active low.</td>
</tr>
<tr>
<td>MII</td>
<td>Indicates that a signal is part of the media independent interface.</td>
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</table>

### Table 22. MPC8250 PBGA Package Pinout List

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Table 22. MPC8250 PBGA Package Pinout List (continued)

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Table 22. MPC8250 PBGA Package Pinout List (continued)

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<td>Pin Name</td>
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### Table 22. MPC8250 PBGA Package Pinout List (continued)

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## Pinout

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Table 22. MPC8250 PBGA Package Pinout List (continued)
Table 22. MPC8250 PBGA Package Pinout List (continued)

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### Table 22. MPC8250 PBGA Package Pinout List (continued)

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</tr>
<tr>
<td>PC5/SI2_L1ST3/FCC2_CTS</td>
<td>AC25^1</td>
</tr>
<tr>
<td>PC6/FCC1_CD</td>
<td>AB25^1</td>
</tr>
<tr>
<td>PC7/FCC1_CTS</td>
<td>AA24^1</td>
</tr>
<tr>
<td>PC8/CD4/RENA4/SI2_L1ST2/CTS3</td>
<td>Y24^1</td>
</tr>
<tr>
<td>PC9/CTS4/CLSN4/SI2_L1ST1/ L1TSYNCA2/L1GNTA2</td>
<td>U22^1</td>
</tr>
<tr>
<td>PC10/CD3/RENA3</td>
<td>V23^1</td>
</tr>
<tr>
<td>PC11/CTS3/CLSN3/L1TXD3A2</td>
<td>U23^1</td>
</tr>
<tr>
<td>PC12/CD2/RENA2</td>
<td>T26^1</td>
</tr>
<tr>
<td>PC13/CTS2/CLSN2</td>
<td>R26^1</td>
</tr>
<tr>
<td>PC14/CD1/RENA1</td>
<td>P26^1</td>
</tr>
<tr>
<td>PC15/CTST1/CLSN1/SMTXD2</td>
<td>P24^1</td>
</tr>
<tr>
<td>PC16/CLK16/TIN4</td>
<td>M26^1</td>
</tr>
<tr>
<td>PC17/CLK15/TIN3/BRGO8</td>
<td>L26^1</td>
</tr>
<tr>
<td>PC18/CLK14/TGATE2</td>
<td>M24^1</td>
</tr>
<tr>
<td>PC19/CLK13/BRGO7/SPICLK</td>
<td>L2^1</td>
</tr>
<tr>
<td>PC20/CLK12/TGATE1</td>
<td>K25^1</td>
</tr>
<tr>
<td>PC21/CLK11/BRGO6</td>
<td>J25^1</td>
</tr>
<tr>
<td>PC22/CLK10/DONE1</td>
<td>Q2^1</td>
</tr>
<tr>
<td>PC23/CLK9/BRGO5/DACKT</td>
<td>F26^1</td>
</tr>
<tr>
<td>PC24/CLK8/TOUT4</td>
<td>Q24^1</td>
</tr>
<tr>
<td>PC25/CLK7/BRGO4</td>
<td>E25^1</td>
</tr>
<tr>
<td>PC26/CLK6/TOUT3/TMCLK</td>
<td>Q2^1</td>
</tr>
<tr>
<td>PC27/FCC3_TXD/FCC3_TXD0/CLK5/ BRGO3</td>
<td>B23^1</td>
</tr>
</tbody>
</table>
Table 22. MPC8250 PBGA Package Pinout List (continued)

<table>
<thead>
<tr>
<th>Pin Name</th>
<th>Ball</th>
</tr>
</thead>
<tbody>
<tr>
<td>PC28/CLK4/TIN1/TOUT2/CTS2/CLSN2</td>
<td>E22</td>
</tr>
<tr>
<td>PC29/CLK3/TIN2/BRGO2/CTS1/CLSN1</td>
<td>E21</td>
</tr>
<tr>
<td>PC30/CLK2/TOUTT</td>
<td>D21</td>
</tr>
<tr>
<td>PC31/CLK1/BRGO1</td>
<td>B20</td>
</tr>
<tr>
<td>PD4/BRGO8/FCC3_RTS/SMRXD2</td>
<td>AF23</td>
</tr>
<tr>
<td>PD5/DONE1</td>
<td>AE23</td>
</tr>
<tr>
<td>PD6/DACK1</td>
<td>AB21</td>
</tr>
<tr>
<td>PD7/SMSYN1/FCC1_TXCLAV2</td>
<td>AD23</td>
</tr>
<tr>
<td>PD8/SMRXD1/BRGO5</td>
<td>AD26</td>
</tr>
<tr>
<td>PD9/SMTXD1/BRGO3</td>
<td>Y22</td>
</tr>
<tr>
<td>PD10/L1CLKOB2/BRGO4</td>
<td>AB24</td>
</tr>
<tr>
<td>PD11/LTRQBE2</td>
<td>Y23</td>
</tr>
<tr>
<td>PD12</td>
<td>AA26</td>
</tr>
<tr>
<td>PD13</td>
<td>W24</td>
</tr>
<tr>
<td>PD14/L1CLKOC2/I2CSCL</td>
<td>V22</td>
</tr>
<tr>
<td>PD15/LTRQCE2/I2CSDA</td>
<td>U26</td>
</tr>
<tr>
<td>PD16/SPIMISO</td>
<td>T25</td>
</tr>
<tr>
<td>PD17/BRGO2/SPIMOSI</td>
<td>R25</td>
</tr>
<tr>
<td>PD18/SPICLK</td>
<td>P23</td>
</tr>
<tr>
<td>PD19/SPISEL/BRGO1</td>
<td>N21</td>
</tr>
<tr>
<td>PD20/RTS4/TENA4/L1RSYNCA2</td>
<td>M25</td>
</tr>
<tr>
<td>PD21/TXD4/L1RXD0A2/L1RXDA2</td>
<td>L25</td>
</tr>
<tr>
<td>PD22/RXD4L1TXD0A2/L1TXDA2</td>
<td>J26</td>
</tr>
<tr>
<td>PD23/RTS3/TENA3</td>
<td>K22</td>
</tr>
<tr>
<td>PD24/TXD3</td>
<td>G25</td>
</tr>
<tr>
<td>PD25/RXD3</td>
<td>H24</td>
</tr>
<tr>
<td>PD26/RTS2/TENA2</td>
<td>F24</td>
</tr>
<tr>
<td>PD27/TXD2</td>
<td>H22</td>
</tr>
<tr>
<td>PD28/RXD2</td>
<td>B22</td>
</tr>
<tr>
<td>PD29/RTS1/TENA1</td>
<td>D21</td>
</tr>
<tr>
<td>PD30/TXD1</td>
<td>C21</td>
</tr>
<tr>
<td>PD31/RXD1</td>
<td>E19</td>
</tr>
<tr>
<td>VCCSYN</td>
<td>D19</td>
</tr>
<tr>
<td>VCCSYN1</td>
<td>K6</td>
</tr>
<tr>
<td>GNDSYN</td>
<td>B18</td>
</tr>
</tbody>
</table>

MPC8250 Hardware Specifications, Rev. 2

Freescale Semiconductor
## Package Description

The following sections provide the package parameters and mechanical dimensions.

### Table 22. MPC8250 PBGA Package Pinout List (continued)

<table>
<thead>
<tr>
<th>Pin Name</th>
<th>Ball</th>
</tr>
</thead>
<tbody>
<tr>
<td>CLKN2</td>
<td>K21</td>
</tr>
<tr>
<td>SPARE4²</td>
<td>C14</td>
</tr>
<tr>
<td>PCI_MODE³</td>
<td>AD24</td>
</tr>
<tr>
<td>SPARE6²</td>
<td>B15</td>
</tr>
<tr>
<td>THERMAL0⁴</td>
<td>E17</td>
</tr>
<tr>
<td>THERMAL1⁴</td>
<td>C23</td>
</tr>
<tr>
<td>I/O power</td>
<td>E6, F6, H6, L5, L6, P6, T6, U6, V5, V5, AA6, AA8, AA10, AA11, AA14, AA16, AA17, AB19, AB20, W21, U21, T21, P21, N21, M22, J22, H21, F21, F19, F17, E16, F14, E13, E12, F10, E10, E9</td>
</tr>
<tr>
<td>Core Power</td>
<td>L3, V4, W3, AC11, AD11, AB15, U25, T24, J24, H25, F23, B19, D17, C17, D10, C10</td>
</tr>
</tbody>
</table>

1 The default configuration of the CPM pins (PA[0–31], PB[4–31], PC[0–31], PD[4–31]) is input. To prevent excessive DC current, it is recommended to either pull unused pins to GND or VDDH, or to configure them as outputs.

2 Must be pulled down or left floating.

3 If PCI is not desired, must be pulled up or left floating.

4 For information on how to use this pin, refer to MPC8260 PowerQUICC II Thermal Resistor Guide (AN2271/D).
5.1 Package Parameters

Package parameters are provided in Table 23.

<table>
<thead>
<tr>
<th>Package</th>
<th>Devices</th>
<th>Outline (mm)</th>
<th>Type</th>
<th>Interconnects</th>
<th>Pitch (mm)</th>
<th>Nominal Unmounted Height (mm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>ZU</td>
<td>MPC8250</td>
<td>37.5 × 37.5</td>
<td>TBGA</td>
<td>480</td>
<td>1.27</td>
<td>1.55</td>
</tr>
<tr>
<td>VV</td>
<td></td>
<td></td>
<td>TBGA (Pb free)</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>ZO</td>
<td></td>
<td>27 × 27</td>
<td>PBGA</td>
<td>516</td>
<td>1</td>
<td>2.25</td>
</tr>
<tr>
<td>VR</td>
<td></td>
<td></td>
<td>PBGA (Pb free)</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

5.2 Mechanical Dimensions

This section discusses the TBGA and PBGA package dimensions.
5.2.1 TBGA Package Dimensions

Figure 17 provides the mechanical dimensions and bottom surface nomenclature of the 480 TBGA package.

<table>
<thead>
<tr>
<th>Dim</th>
<th>Millimeters</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
<td>1.45</td>
</tr>
<tr>
<td>A1</td>
<td>0.60</td>
</tr>
<tr>
<td>A2</td>
<td>0.85</td>
</tr>
<tr>
<td>A3</td>
<td>0.25</td>
</tr>
<tr>
<td>b</td>
<td>0.65</td>
</tr>
<tr>
<td>D</td>
<td>37.50 BSC</td>
</tr>
<tr>
<td>D1</td>
<td>35.56 REF</td>
</tr>
<tr>
<td>e</td>
<td>1.27 BSC</td>
</tr>
<tr>
<td>E</td>
<td>37.50 BSC</td>
</tr>
<tr>
<td>E1</td>
<td>35.56 REF</td>
</tr>
</tbody>
</table>

Notes:
2. Dimensions in millimeters.
3. Dimension b is measured at the

Figure 17. Mechanical Dimensions and Bottom Surface Nomenclature—480 TBGA
5.2.2 PBGA Package Dimensions

Figure 18 provides the mechanical dimensions and bottom surface nomenclature of the 516 PBGA package.

Figure 18. Mechanical Dimensions and Bottom Surface Nomenclature—516 PBGA
6 Ordering Information

Figure 19 provides an example of the Freescale part numbering nomenclature for the MPC8250. In addition to the processor frequency, the part numbering scheme also consists of a part modifier that indicates any enhancement(s) in the part from the original production design. Each part number also contains a revision code that refers to the die mask revision number and is specified in the part numbering scheme for identification purposes only. For more information, contact your local Freescale sales office.

![Part Number Key](image)

Figure 19. Freescale Part Number Key

7 Document Revision History

Table 24 provides a revision history for this template.

<table>
<thead>
<tr>
<th>Revision</th>
<th>Date</th>
<th>Substantive Changes</th>
</tr>
</thead>
<tbody>
<tr>
<td>2</td>
<td>7/2009</td>
<td>Updated TBGA and PBGA packaging information.</td>
</tr>
<tr>
<td>1</td>
<td>3/2005</td>
<td>Document template update</td>
</tr>
</tbody>
</table>
| 0.9      | 8/2003 | • Table 2: Modification to supply voltage ranges reflected in notes 2, 3, and 4  
<pre><code>      |        | • Addition of VCCSYN to “Note: Core, PLL, and I/O Supply Voltages” following Table 2 |
</code></pre>
<p>|          |        | • Addition of Figure 2                                                             |
|          |        | • Addition of note 1 to Table 3                                                   |
|          |        | • Table 4: Changes to ( \theta_{JA} ), Addition of ( \theta_{JB} ) and ( \theta_{JC} ) |
|          |        | • Table 7, Figure 8: Addition of sp42a/sp43a                                      |
|          |        | • Figure 3 through Figure 8: Addition of notes or modifications                    |
|          |        | • Table 9: Change to sp10                                                          |
|          |        | • Table 14, Table 16, and Table 18: Removal of PLL bypass mode from clock tables   |
|          |        | • Table 20 and Table 22: Addition of note 1                                        |
|          |        | • Addition of SPICLK to PC19 in Table 20 and Table 22. It is documented correctly in the |
|          |        | MPC8260 PowerQUICC II™ Family Reference Manual but had previously been omitted from |
|          |        | Table 20 and Table 22.                                                            |
| 0.8      | 11/2002| Table 22, “VR Pinout”: Addition of C18 to the Ground (GND) pin list (page 53)     |
| 0.7      | 10/2002| Table 22, “VR Pinout”: Addition of L3 to the Core (VDDx) pin list (page 53)       |</p>
<table>
<thead>
<tr>
<th>Revision</th>
<th>Date</th>
<th>Substantive Changes</th>
</tr>
</thead>
<tbody>
<tr>
<td>0.6</td>
<td>10/2002</td>
<td>Table 22, “VR Pinout”: corrected ball assignment for the following pins—A12–A17, TA, PD5, PC2.</td>
</tr>
<tr>
<td>0.5</td>
<td>9/2002</td>
<td>Addition of VR (516 PBGA) package information. Refer to sections 2.2, 4.2, and 5.</td>
</tr>
</tbody>
</table>
| 0.4      | 5/2002  | • Table 2: Notes 2 and 3  
• Addition of note on page 8: VDDH and VDD tracking  
• Table 14: Note 3  
• Table 16: Note 1  
• Table 18: Note 3 |
| 0.3      | 3/2002  | • Table 20: modified note to pin AF25.                                               |
| 0.2      | 3/2202  | • Table 20: modified notes to pins AE11 and AF25.  
• Table 20: added note to pins AA1 and AG4 (Therm0 and Therm1). |
| 0.1      | 2/2002  | • Note 2 for Table 4 (changes in italics): “…greater than or equal to 266 MHz, 200 MHz CPM…”  
• Table 18: core and bus frequency values for the following ranges of MODCK_HMODCK:  
  0011_000 to 0011_100 and 1011_000 to 1011_1000  
• Table 20: footnotes added to pins at AE11, AF25, U5, and V4. |
| 0        | 11/2001 | Initial version                                                                     |
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